

# **LOCTITE ABLESTIK ATB 120US1**

July 2019

#### PRODUCT DESCRIPTION

LOCTITE ABLESTIK ATB 120US1 provides the following product characteristics:

Technology	Epoxy Film	
Appearance	Transparent	
Cure	Skip-Cure Process	
Product Benefits	<ul> <li>Long thermal budget</li> </ul>	
	<ul> <li>Meets thin wafer requirements</li> </ul>	
	Co-curable during molding process	
	<ul> <li>Consistent dicing and die pickup for large die applications</li> </ul>	
Application	Encapsulation or Semi-Films	
Filler Type	Silica	
Typical Package	Die to die stack and Die to substrate	
Application		
Carrier Type	Polyolefin	
Adhesive Thickness	20μm	
Carrier Film Thickness	90µm	
Wafer Size in	8 and 12 in	

LOCTITE ABLESTIK ATB 120US1 adhesive film with UV dicing tape is formulated for use in wafer lamination processes or as a preform decal.

It is designed for use in both mother/daughter die in stack packages.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

Work Life @ 25°C, days	90
Shelf Life @ 5°C (from date of manufacture), days	365

#### TYPICAL PROCESS DATA

#### **Wafer Backside Lamination**

Temperature, °C	65
Pressure, psi	30
Taping Duration, ft/ minute	1

#### Chip Attach

Temperature, °C	100 to 130
Pressure, kg-f	0.5 to 1.0
Attach Duration, second	0.5 to 1.0

## TYPICAL UV IRRADIATION

U	V	Li	g	ht

UV Dosage, mJ/cm²	200
UV Wavelength, nm (UVA)	365

#### **TYPICAL CURING PERFORMANCE**

#### SkipCure Process

Cured at post mold cure

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

### TYPICAL PROPERTIES OF CURED MATERIAL

#### **Physical Properties**

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Coefficient of Thermal Expansion, TMA:		
Below Tg, ppm/°C		81
Glass Transition Temperature (Tg) by DMTA,	°C	41
Tensile Modulus, DMTA:		
@ -65 °C		3,505 (508,357)
@ 25 °C	N/mm²	1,277 (185,213)
@ 150 °C	N/mm² (psi)	2.4
@ 200 °C	N/mm² (psi)	2.0
@ 250 °C	N/mm² (psi)	1.9
Extractable Ionic Content, :	. ,	,
Chloride (Cl-)		7
Sodium (Na+)		6
Potassium (K+)		2
Weight Loss @ 250°C, %		0.6
Moisture Absorption @ Saturation, after 85 exposure, wt %	°C/85%	RH 1.8

## TYPICAL PERFORMANCE OF CURED MATERIAL

Thermal Budget @ 175°C, hours >4
Die Shear Strength vs Temperature, kg-f:

2.5 X 2.5 mm Si die, kg-f,

Die on Substrate:	@260°C
BT Substrate	1.0

#### **GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.



#### **DIRECTIONS FOR USE**

- Ensure all surfaces to be bonded are free from surface contamination.
- Adhesive must be completely used within the product's recommended work life.
- Remove the tape reel from the moisture-resistant package and load into the tape application machine.
- Store unused adhesive film in the original sealed moistureresistant package until needed.

#### STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

# Optimal Storage: 5°C. Storage below 5°C or greater than 5°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb/F N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·ft N·m x 0.738 = lb·ft N·m x 0.142 = oz·in mPa·s = cP

#### Disclaimer

#### Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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